



EMC'14/Tokyo

May 13-16, 2014

Hitotsubashi Hall (National Center of Sciences),
Tokyo, Japan



2014 International Symposium on Electromagnetic Compatibility, Tokyo



* In view of international EMC conferences, EMC'14/Tokyo will be technically co-operated by APEMC in agreement between APEMC TPC and EMC'14/Tokyo. No separate APEMC will be held in 2014.

Final Call for Papers

About This Symposium

The "2014 International Symposium on Electromagnetic Compatibility" (EMC'14/Tokyo) will be held at "Hitotsubashi Hall (National Center of Sciences)", Chiyoda, Tokyo, from May 13 to 16, 2014. EMC'14/Tokyo is the 7th "International Symposium on Electromagnetic Compatibility" organized by "The Institute of Electronics, Information and Communication Engineers, Communications Society" (IEICE-CS). We would like to invite all engaged in research and development in the various fields of electromagnetic compatibility to participate in this Symposium. This EMC Symposium series has a long history and it has been held every 5 years, celebrating its 30th anniversary this time. The first of its series was held in Tokyo in 1984, which was the first IEEE EMC Symposium held outside USA, sharing sponsorship with IECE (current IEICE). Ever since the second in 1989, this symposium series has been sponsored by IEICE.

Prof. **Masao Taki**, EMC'14/Tokyo General Chair,

Prof. **Osami Wada**, EMC'14/Tokyo Technical Program Committee Chair

Session Topics

1) EMC Measurements:

*Measurement & Instrumentation,
Measurement Techniques,
EMC Test Facilities, Antennas*

2) High Power & High Voltage EMC:

*Lightning & Overvoltage Protection,
Intentional EMI & EMP,
High Power Electromagnetics,
Grounding Phenomena in Power Systems*

3) EMC Management and Standards:

*Standards & Regulations, Electromagnetic
Product Safety, System-Level EMC,
EMC Management, EMC Education*

4) Chip, Package, PCB & Cables:

*IC & Semiconductor EMC,
Electronic Packaging & Interconnection, PCB,
Transmission Lines & Cables,
Power & Signal Integrity*

5) Immunity/Susceptibility, ESD and Transients:

*EMC Tests, EM Radiation, Gap Discharge,
Contact, Surge Protection*

6) Shielding, Grounding & Materials:

*Shielding & Grounding, EM Absorber,
Material in EMC Applications, Meta-materials*

7) Numerical Modeling:

*Computational Electromagnetics,
Large-scale Numerical Simulation,
GPU Simulation*

8) EMF Safety & Biomedical Issues:

*Human exposure to ELF/RF EM fields,
Biological Effects,
Medical Application,
Medical Devices & Hospital Equipment*

9) Power System EMC:

*Smart Grids, Power Quality Issues,
EMC in Power Plants & Substations,
Solar Power Systems, Wireless Power Transmission*

10) Power Electronics & Vehicles:

*Automotive EMC, Electric Vehicle,
Railway & Naval EMC, EMC in Space*

11) Communication System EMC:

*Wired & Wireless Communications, Antennas,
Propagation & Scattering,
Power Line Communications,
Information System Security*

Important Dates

2013 September 15

--- Deadline for Full-length Paper
Submission

2013 November 30

--- Notification of Acceptance

2014 January 31

--- Final Paper and Authors
Registration Deadline

* The paper submission deadline has
been changed to September 15.

* Organized session topics will be listed after the middle of July, 2013, to jointly arrange some Organized and Regular Sessions.

* After the symposium, all accepted and presented papers will be included in the "IEICE Proceedings Archives", the "IEICE Knowledge Discovery (I-Scover)", and the "IEEE Xplore", based on the agreement between IEICE and IEEE. "No-show (not presented)" papers, however, will not be considered to be included in such databases.

Paper Submission

Each one of those who wish to present their scientific work at EMC'14/Tokyo should submit a full-length (4 pages) preliminary paper in a PDF file through the on-line Paper Submission System at the symposium website. The paper must follow the two-column A4 format of an IEEE Manuscript Template for the Symposium Proceedings. There are two types of scientific sessions for EMC'14/Tokyo; “Regular Sessions” and “Organized Sessions”. The Regular Sessions will consist of contributed papers only, while the Organized Sessions will be arranged by the Session Organizers (see our website).

When submitting a paper for the Regular Sessions, the author will be asked to select “2” session topics that would best match the contents of his/her paper for review. There are “11” Regular Session topics, and Organized Session topics will be added after the middle of July, 2013, to help make some Organized and Regular Sessions jointly arranged in the technical program. Submission for contributed papers will start on June, 2013, with the deadline on **September 15, 2013**. All the contributed papers will be fully reviewed by specialists in the EMC field, and the review results will be notified to the authors on November 30, 2013. The authors of accepted papers must register for EMC'14/Tokyo and submit the final camera-ready versions of their papers **no later than January 31, 2014**.

EMC'14/Tokyo Awards

All the contributed papers in the Regular Sessions are eligible to be considered for the EMC'14/Tokyo Awards: (1) Risaburo Sato Award; to honor the author(s) of the most outstanding regular paper selected on the basis of originality and technical excellence, (2) Excellent Paper Award; to honor the authors of papers judged to be of high merit, (3) Young Researcher Award; to honor the young authors (must be less than 33 years of age at the Symposium) who have submitted outstanding work in the EMC field, and (4) IEEE EMC Society Japan and Sendai Chapters Student Award; to honor the authors who possess the IEEE Student Membership, belonging to either of the two chapters, and also who have submitted outstanding work in the EMC field. Detailed information about the awards will be updated on the website later.

Registration Fees

	Regular	Student
Pre-Registration for Presenters (from Nov. 30, 2013 to Jan. 31, 2014)	47,000 JPY	25,000 JPY
Pre-Registration for Participants (from Nov. 30, 2013 to Apr. 20, 2014)		
On-site Registration for Participants (from May 12 to 16, 2014)	57,000 JPY	30,000 JPY

- * All the registration fees must be paid in Japanese yen (JPY).
- * Each one of the accepted papers including the Organized Session papers should have a pre-registered presenter by January 31, 2014. The presenter must be one of the co-authors.
- * The presenters who wish to give multiple paper presentations at the Regular Sessions should pre-register "1" time, but must pay an additional fee of 25,000 JPY per paper for the second and subsequent papers.
- * Please check our web site (<http://www.ieice.org/~emc14/>) for other details.

Sponsored by:

The Institute of Electronics, Information and Communication Engineers, Communications Society (IEICE-CS)

Technically Co-sponsored by:

IEEE EMC Society; Technical Committee on EMC of The Institute of Electrical Engineers of Japan (IEEJ TC-EMC)

Technically Co-operated by:

IEEE EMC-S Japan and Sendai Chapters; IEEE Tokyo Section; Asia-Pacific International Symposium on Electromagnetic Compatibility, Technical Program Committee (APEMC TPC); The Korean Institute of Electromagnetic Engineering and Science (KIEES), Technical Groups on "EMC Technology" and "EMF and Biology"; International Union of Radio Science (URSI); IEC, Technical Committee on Electromagnetic Compatibility (IEC/TC77); IEC, Technical Committee on Methods for the Assessment of Electric, Magnetic, and Electromagnetic Fields Associated with Human Exposure (IEC/TC106); International Special Committee on Radio Interference (CISPR); VCCI Council; The Japan Institute of Electronics Packaging (JIEP); The Japan Society of Applied Physics (JSAP); The Society of Instrument and Control Engineers (SICE); The Institute of Electrostatics Japan (IEJ); Japanese Society for Medical and Biological Engineering (JSMBE)

Supported by:

Ministry of Internal Affairs and Communications, Japan; Ministry of Education, Culture, Sports, Science and Technology, Japan; Ministry of Economy, Trade and Industry, Japan; Ministry of Land, Infrastructure, Transport and Tourism, Japan (being processed)

EMC'14/Tokyo Secretariat

c/o Dupler Corp.
 3F Sun-Arch Bldg., 3-1 Nemoto, Matsudo, Chiba 271-0077, Japan
 Phone: +81-47-361-6030, Fax: +81-47-308-5272
 E-mail: emc14-office@mail.emcjp-symposium.org

Information and Contact

E-mail emc14-contact@mail.ieice.org
 Website <http://www.ieice.org/~emc14/>

